





# ANDS4E38XX20 InGaAIP Ultra Bright Yellow Light Emission T-1 3/4 Package (5 mm)

## Features

- Peak wavelength (lp = 590 nm) ultra bright emission
- All plastic mold type, clear colorless lens
- Low drive current: 1 to 20 mA DC
- Excellent On-Off contrast ratio
- Fast response time, capable of pulse operation
- · High power luminous intensity
- Suitable for Outdoor Message Signboards
- High reliability, storage temperature -40 to +100°C

#### Maximum Ratings (T<sub>a</sub> = 25°C)

Characteristics	Symbol	Rating	Unit	
Forward Current	١ <sub>F</sub>	50	mA	
Reverse Voltage	V <sub>R</sub>	5	V	
Power Dissipation	PD	125	mW	
Operating Temperature Range	T <sub>Opr</sub>	-40 to 85	°C	
Storage Temperature Range	T <sub>Stg</sub>	-40 to 100	°C	

### Electro-Optical Characteristics (T<sub>a</sub> = 25°C)

Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20 mA	-	2.1	2.8	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 4 V	-	-	50	μA
Luminous Intensity	Ι <sub>V</sub>	I <sub>F</sub> = 20 mA	2,000	3,000	-	mcd
Peak Emission Wavelength	۱ <sub>Р</sub>	I <sub>F</sub> = 20 mA	-	590	-	nm
Spectral Line Half Width	Δl	I <sub>F</sub> = 20 mA	-	15	-	nm
Dominant Wavelength	ld	I <sub>F</sub> = 20 mA	-	587	-	nm
Full Viewing Angle	q	I <sub>V</sub> = 1/2 Peak	_	20	_	degree

#### Precaution

Please be careful of the following:

- 1. Soldering temperature: 260°C max
  - Soldering time: 5 sec. max
  - Soldering portion of lead: up to 1.6 mm from the body of the device
- 2. The lead can be formed up to 5 mm from the body of the device without forming stress. Soldering should be performed after the lead forming.

Product specifications contained herein may be changed without prior notice.

It is therefore advisable to contact Purdy Electronics before proceeding with the design of equipment incorporating this product.